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CLAIMS

1-10. (Cancelled)

11. (Previously Presented) A wafer comprising a glide head array including a plurality of rows and a plurality of columns of glide portions having air bearing surfaces formed on a surface of the wafer and an array of glide transducers on the wafer to form a plurality of glide heads.

12. (Previously Presented) The wafer of claim 11 wherein the array of air bearing surfaces comprise rails.

13. (Previously Presented) The wafer of claim 11 wherein said surface of the wafer has a flatness less than about 3 μ m.

14. (Original) The wafer of claim 11 wherein the wafer comprises aluminum oxide/titanium carbide.

15. (Previously Presented) The wafer of claim 11 wherein the surface of the wafer has a peak-to-valley flatness less than about 1 μ inch.

16. (Previously Presented) The wafer of claim 11 wherein the surface of the wafer has a surface flatness less than about 1 μ inch.

17. (Previously Presented) A wafer comprising a glide head array including a plurality of rows and a plurality of columns of glide portions having air bearing surfaces formed on a surface of the wafer and an array of glide transducers on the wafer to form a plurality of glide heads wherein the array of glide transducers are mounted on a wafer surface opposite to the surface of the wafer having the air bearing surfaces formed thereon.

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18. (Previously Presented) The wafer of claim 11 wherein the surface of the wafer has a flatness less than about 0.5 μ inch.

19. (Previously Presented) A glide head formed from the a wafer comprising a plurality of rows and a plurality of columns of glide portions having a plurality of air bearing surfaces formed on a surface of the wafer and an array of glide transducers on the wafer and the glide head formed from one of said glide portions.

20. (Previously Presented) A detection system for detecting asperities comprising the glide head of claim 19 supported on an armature operable to position the glide head over a disc surface for glide testing and including a transducer on the glide head to detect interactions between the glide head and the disc surface.

21. (Previously Presented) The wafer of claim 11 where the array of glide transducers includes an array of piezoelectric transducers.

22. (Previously Presented) The wafer of claim 17 wherein the glide head array includes an array of wing portions and the array of glide transducers are formed thereon.

23. (Previously Presented) The wafer of claim 11 wherein the array of glide transducers are formed on the surface of the wafer having the air bearing surfaces formed thereon.

24. (Previously Presented) A wafer comprising a glide head array including a plurality of rows and a plurality of columns of glide portions having air bearing surfaces formed on a surface of the wafer and an array of glide transducers on the wafer to form a

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plurality of glide heads wherein the array of glide transducers includes an array of thermal transducers formed on a surface of the wafer having the air bearing surfaces formed thereon.

25. (Previously Presented) The wafer of claim 24 wherein the thermal transducers of the array of thermal transducers are formed of magnetoresistive sensors.

26. (Previously Presented) The wafer of claim 11 wherein the air bearing surfaces of the plurality of rows and the plurality of columns of glide portions are formed using one of or a combination of saw cutting,

27. (Previously Presented) The wafer of claim 11 wherein the glide head array includes an array of wing portions and the array of glide transducers are formed thereon.